PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Yaojian Lin	01/29/2013
Pandi Chelvam Marimuthu	01/29/2013
Kang Chen	01/29/2013
Yu Gu	01/29/2013

RECEIVING PARTY DATA

Name:	STATS ChipPAC, Ltd.
Street Address:	10 Ang Mo Kio Street 65
Internal Address:	#05-17/20 Techpoint
City:	Singapore
State/Country:	SINGAPORE
Postal Code:	569059

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13759911

OP $40.00 13759911

CORRESPONDENCE DATA

Fax Number: 4804999456
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
Phone: 480-499-9400
Email: main@plgaz.com
Correspondent Name: PATENT LAW GROUP: Atkins & Associates
Address Line 1: 605 W. Knox Road
Address Line 2: Suite 104
Address Line 4: Tempe, ARIZONA 85284

ATTORNEY DOCKET NUMBER:	2515.0413
NAME OF SUBMITTER:	Robert D. Atkins

Total Attachments: 4
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ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, YAOJIAN LIN of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING STRESS RELIEVING VIAS FOR IMPROVED FAN-OUT WLCSP PACKAGE, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0413, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above-identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above-identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

I hereby authorize and request the government authority in the United States to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, to STATS ChipPAC, for the sole use and behalf of STATS ChipPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the United States to issue the patents of their respective countries to and in the name of STATS ChipPAC in the same manner.

I agree that, when requested, I will, without charge to STATS ChipPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto in STATS ChipPAC, its successors, assigns, and legal representatives or nominees.

I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.

Signature for YAOJIAN LIN

Witnessed on this date: 29 JAN 2013

Signature of Witness:

Printed Name of Witness: DIOSCORO MERILO

Address of Witness: 5 YISHUN STREET 23
SINGAPORE 768442

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, PANDI CHELVAM MARIMUTHU of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled <u>SEMICONDUCTOR DEVICE AND METHOD OF FORMING STRESS RELIEVING VIAS FOR IMPROVED FAN-OUT WLCSP PACKAGE</u>, which is described, illustrated, and claimed in any patent application under Attorney Docket No. <u>2515.0413</u>, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above-identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above-identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

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I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.

Signature for PANDI CHELVAM MARIMUTHU

Witnessed on this date: 29 JAN 2013

Signature of Witness:

Printed Name of Witness: DIOSCORO MERILO

Address of Witness: 5 YISHUN STREET 23

SINGAPORE 768442

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, KANG CHEN of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING STRESS RELIEVING VIAS FOR IMPROVED FAN-OUT WLCSP PACKAGE, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0413, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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Chen Kang
Signature for KANG CHEN

Witnessed on this date: 29 JAN 2013

Signature of Witness:
Printed Name of Witness: DIOSCORO MERILO
Address of Witness: 5 YISHUN STREET 23
SINGAPORE 768442

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, YU GU of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING STRESS RELIEVING VIAS FOR IMPROVED FAN-OUT WLCSP PACKAGE, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0413, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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Signature for YU GU

Witnessed on this date: 29 JAN 2013

Signature of Witness:

Printed Name of Witness: DIOSCORO MERILO

Address of Witness: 5 YISHUN STREET 23
SINGAPORE 768442